Product Change Notification

Change Notification #: 115288 - 00

Change Title: **Intel® Omni-Path Host Fabric Interface Adapter 100 Series 2 Port Split PCIe x16 Low Profile 100HFA02TLS,**

Intel® Omni-Path Host Fabric Interface Adapter 100 Series 2 Port Split PCIe x16 Standard 100HFA02TFS,

PCN 115288-00, Product Design, Label, Product Material,

Regulatory Label update for Korea/Taiwan and Firmware Upgrade

Date of Publication: **February 14, 2017**

Key Characteristics of the Change:

Product Design, Product Material, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	March 1, 2017

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Affected Product Code	Product Description
100HFA02TLS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 2 Port Split PCIe x16 Low Profile 100HFA02TLS
100HFA02TFS	Intel® Omni-Path Host Fabric Interface Adapter 100 Series 2 Port Split PCIe x16 Standard 100HFA02TFS

Overview of Changes:

<u>Change 1:</u> Regulatory and Compliance Certifications were successfully acquired from Korea and Taiwan. The changes include the following:

- A. The regulatory label for the product will be updated with the Korean (KC/MSIP) and Taiwan (BSMI) marks.
- B. The Read Me First document will be updated to add the Regulatory Model Numbers.
- C. The packaging label will be updated to reflect the KC labelling requirements

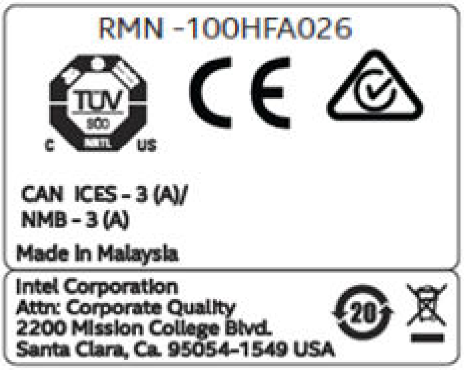
<u>Change 2:</u> The firmware shall be updated as follows, (reference release notes for 10.1 and 10.3):

- A. OptionROM UEFI firmware version 0x1C shall be replaced with version 1.3.0.0.0
- B. OptionROM UNDI firmware version 0x1C shall be replaced with version 1.3.0.0.0
- C. OptionROM Config version 10.1.0.0.129 shall be replaced with version 1.0.1.0
- D. TMM firmware version 10.1.0.0.101 shall be replaced with version 10.2.1.0.3

Product Material Change Details:

<u>Change 1A</u>: Regulatory Label showing the addition of the Korean and Taiwanese marks.

Before:

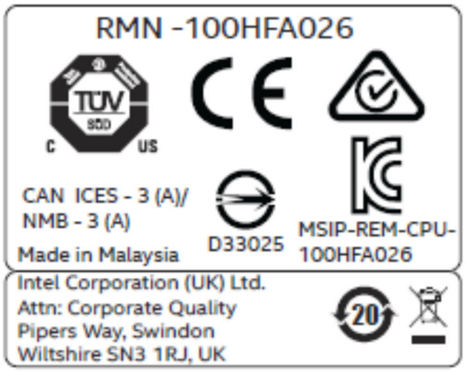


RMN -100HFA026

CAN ICES - 3 (A)/
NMB - 3 (A)
Made in Malaysia

Intel Corporation
Attn: Corporate Quality
2200 Mission College Blvd.
Santa Clara, Ca. 95054-1549 USA

After:



RMN -100HFA026

CAN ICES - 3 (A)/
NMB - 3 (A)
Made in Malaysia

D33025

MSIP-REM-CPU-
100HFA026

Intel Corporation (UK) Ltd.
Attn: Corporate Quality
Pipers Way, Swindon
Wiltshire SN3 1RJ, UK

Change 1B: Regulatory change showing the addition of the Regulatory Model Numbers to the Read Me First Document

Before:

Safety and Compliance
Regulatory Compliance Statements

Federal Communications Commission (FCC) Class A Statement

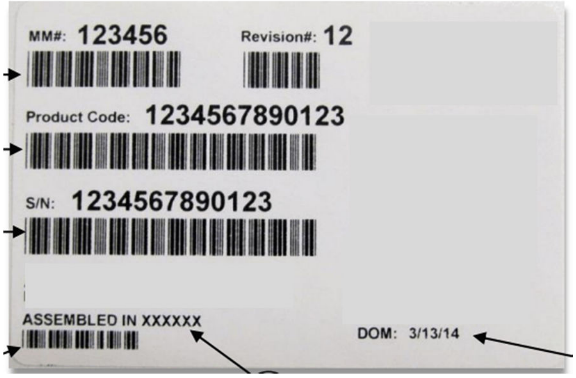
After:

Safety and Compliance
Regulatory Compliance Statements
Regulatory Model Numbers: 100HFA016, 100HFA018,
100HFA026

Federal Communications Commission (FCC) Class A Statement

Change 1C: Package Label change to accommodate the Korean Regulatory requirements.

Before:



MM#: 123456 Revision#: 12

Product Code: 1234567890123

S/N: 1234567890123

ASSEMBLED IN XXXXXX

DOM: 3/13/14

After:

The following data will be added to the existing package label for Korean requirements:

1. KC Mark
2. Korean Registration Number: MSIP-REM-CPU-100HFA026
3. Equipment Name: Intel Omni-Path Host Fabric Interface Adapter
4. Regulatory Model Number: 100HFA026
5. Applicant: Intel Corporation
6. Manufacturer: Flextronics Technology

The following data will be added to the existing package label for European Union requirements:

1. CE Mark
2. Intel European Address

Similar to:

MM #:945670 MM Rev #: 09

Product Code:100HFA018LS

S/N:MYFM48163486D AS J12507-012

Qty:1

MSIP-REM-CPU-100HFA026
Intel Omni-Path Host Fabric Interface Adapter
Model : 100HFA018
Applicant: Intel Corporation
Manufacturer: Flextronics Technology

For CE mark related questions:
Intel Corporation (UK) Ltd.,
Attn: Corp Quality
Pipers Way
Swindon, Wiltshire SN3 1RJ, UK

MADE IN MALAYSIA WITH PARTIAL FOREIGN CONTENT
DOM: 11/29/16

Change 2: The firmware shall be updated as follows:

A. OptionROM UEFI firmware version 0x1C shall be replaced with version 1.3.0.0.0
B. OptionROM UNDI firmware version 0x1C shall be replaced with version 1.3.0.0.0
C. OptionROM Config file version 10.1.0.0.129 shall be replaced with version 1.0.1.0
D. TMM firmware version 10.1.0.0.101 shall be replaced with version 10.2.1.0.3

Customer Impact of Change and Recommended Action:

Intel is not recommending additional qualification of these changes by customers.
There is no change to the adapter Intel Material Master (MM) numbers.
Please contact your local Intel Field Sales Representative if you have any questions about this change.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change MM# Rev	Post Change MM# Rev	Pre Change TA	Post Change TA	Pre Change AS	Post Change AS
100HFA02TLS	946324	10	11	J12633-018	J12633-019	J12632-018	J12632-020
100HFA02TFS	946325	02	03	J31076-002	J31076-003	J31075-002	J31075-003

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
February 14, 2017	00	Originally Published PCN

Product Change Notification
115288 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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